

Product data sheet

Specifications



dPAC controller, Modicon M580, standard, integrated RAM 64 MB

BMED581020

Main

Range of product	Modicon M580
Product or component type	Processor module

Complementary

Number of racks	4
Local I/O processor capacity (discrete)	1024 I/O
Local I/O processor capacity (analog)	64 I/O
Integrated connection type	1 Ethernet TCP/IP for service port 2 Ethernet TCP/IP for device network
Number of distributed equipment	64
Memory description	Integrated RAM, 64 MB for program and data
Current consumption	295 mA at 24 V DC
MTBF reliability	600000 H
Marking	CE

Environment

Vibration resistance	3 gn
Shock resistance	30 gn
Ambient air temperature for operation	0...60 °C
Ambient air temperature for storage	-40...85 °C
Operating altitude	0...2000 m 2000...5000 m with derating factor
Relative humidity	5...95 % at 55 °C without condensation
IP degree of protection	IP20
Directives	2014/35/EU - low voltage directive 2014/30/EU - electromagnetic compatibility 2006/42/EC - machinery
Product certifications	CE UL CSA EAC
Standards	IEC 61131-2 IEC 61010-2-201 UL 61010-2-201 IACS E10
Environmental characteristic	Hazardous location class I division 2

Supply	Internal power supply via rack
Status LED	1 LED (green) processor running (RUN) 1 LED (red) processor or system fault (ERR) 1 LED (red) I/O module fault (I/O) 1 LED (green) download in progress (DL) 1 LED (red) I/O values overridden by user (FORCED IO) 1 LED (green/red) ETH MS (Ethernet port configuration status) 1 LED (green/red) Eth NS (Ethernet network status)
Net weight	0.849 kg

Packing Units

Unit Type of Package 1	PCE
Number of Units in Package 1	1
Package 1 Height	9.000 cm
Package 1 Width	18.000 cm
Package 1 Length	25.200 cm
Package 1 Weight	875.000 g
Unit Type of Package 2	S03
Number of Units in Package 2	6
Package 2 Height	30.000 cm
Package 2 Width	30.000 cm
Package 2 Length	40.000 cm
Package 2 Weight	5.798 kg

Environmental Data

Schneider Electric aims to achieve Net Zero status by 2050 through supply chain partnerships, lower impact materials, and circularity via our ongoing “Use Better, Use Longer, Use Again” campaign to extend product lifetimes and recyclability.

[Environmental Data explained >](#)

[How we assess product sustainability >](#)

Environmental footprint

Total lifecycle Carbon footprint 247

Environmental Disclosure [Product Environmental Profile](#)

Use Better

Materials and Substances

Packaging made with recycled cardboard Yes

Packaging without single use plastic No

[EU RoHS Directive](#) Pro-active compliance (Product out of EU RoHS legal scope)

SCIP Number 4eb70ab0-978b-4773-a441-0cc20d6144a1

REACH Regulation [REACH Declaration](#)

California proposition 65 **WARNING:** This product can expose you to chemicals including: Lead and lead compounds, which is known to the State of California to cause cancer and birth defects or other reproductive harm. For more information go to www.P65Warnings.ca.gov

Use Again

Repack and remanufacture

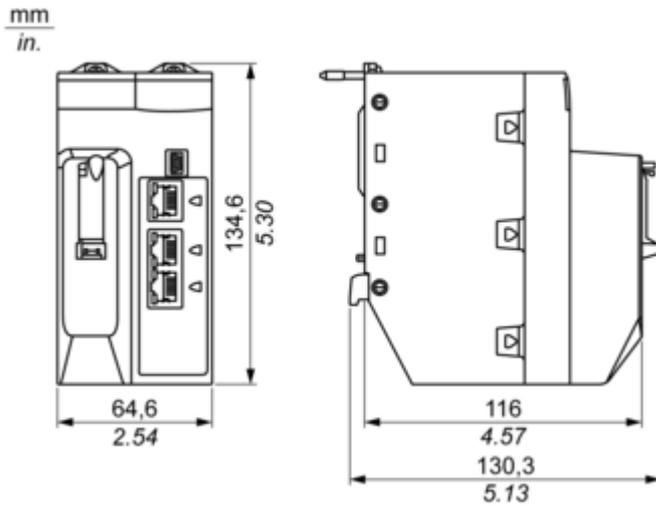
End of life manual availability [End of Life Information](#)

Take-back No

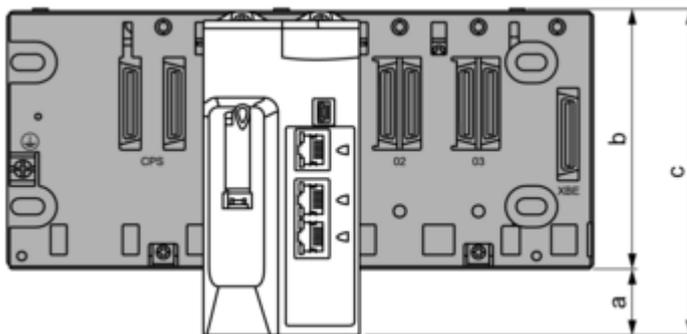
Dimensions Drawings

Dimensions

CPU Module Only



Modules Mounted on Racks

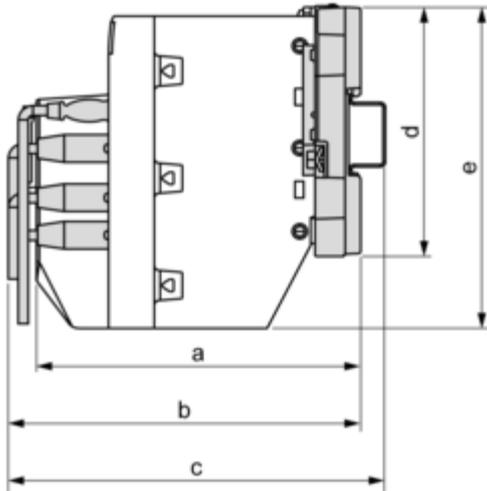


a: additional space below the rack to accommodate the height of the CPU. For an X Bus rack, the value is 30.9 mm (1.217 in.); for an Ethernet rack, the value is 29.49 mm (1.161 in.).

b: the height of the rack. For an X Bus rack, the height is 103.7 mm (4.083 in.); for an Ethernet rack, the height is 105.11 mm (4.138 in.).

c: the height of the main local rack, 134.6 mm (5.299 in.)

Modules and Cables Mounted in an Enclosure



a: enclosure depth: 135 mm (5.315 in.)

b: wiring + module depth: > 146 mm (5.748 in.)

c: wiring + module + DIN rail depth: > 156 mm (6.142 in.)

d: rack height: for an X Bus rack 103.7 mm (4.083 in.); for an Ethernet rack, 105.11 mm (4.138 in.)

e: module height: 134.6 mm (5.299 in.)

Image of product / Alternate images

Alternative

